

Appn. No. 09/655,893

Attorney Docket No. 10541-2085

**I. Amendments to the Specification**

Please replace the paragraph beginning at page 13, line 24, with the following amended paragraph:

Referring now to Figures 4(a)-(e), there is shown a method for interconnecting layers of a circuit assembly 110, which is performed in accordance with the teachings of the preferred embodiment of the invention. Circuit assembly 110 is formed by "building up" or sequentially adding various layers of certain materials to a "substrate" portion 112 (a first pre-circuit assembly), which is substantially identical to substrate portion 52. Particularly, substrate portion 112 includes a ground layer or core metal portion 114, which is preferably manufactured and/or formed from a conventional solderable material (e.g. copper). A dielectric layer 116 is attached/coupled to the top surface of conductive layer 114 in a conventional manner, and a conventional adhesive layer 118 is applied to and substantially covers the top surface of layer 116.

Please replace the paragraph beginning at page 14, line 13 with the following amended paragraph:

In the first step of the process, as shown in Figure 4(a), through holes or vias 120 are formed through substrate portion 112 in a conventional manner (e.g., by drilling). The through holes 120 are formed in locations where connections between ground member 114 and other portions of the circuit 110 are desired to be formed. After vias 120 are formed, a second pre-circuit assembly 124 is attached to substrate portion 112, as shown in Figure 4(b). Assembly 124 (a second pre-circuit assembly) includes a core

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metal portion 126, which is preferably manufactured and/or formed from a conventional aluminum material, and a pair of electrically conductive layers 128, 130 which are respectively attached to the opposing surfaces (e.g., top and bottom surfaces) of core metal portion 126 and which are preferably manufactured and/or formed from a conventional solderable material (e.g. copper). Pre-circuit assembly 124 is registered with respect to holes 120 such that a portion of conducting layer 128 resides above each hole 120 and such that conducting layer 130 does not reside above either hole 120 (e.g., portions of conducting layer 128 which are desired to be connected to ground member 114 are aligned with through holes 120). Pre-circuit assembly 124 is then attached to adhesive layer 118 which operatively bonds the conductive layer 128 of pre-circuit assembly 124 to dielectric layer 116. When pre-circuit assembly 124 is attached to dielectric layer 116, portions of conductive layer 128 which are to be connected to core member [[84]] 114 (e.g. portions 132) extend within or above apertures 120. In one non-limiting embodiment of the invention, pre-circuit assembly 124 and/or electrically conductive member 128 is connected, coupled, and/or attached to adhesive material 118 by use of a known and conventional laminating process such as a conventional "one-step" laminating process.